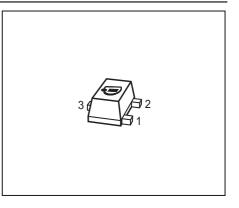


NPN Silicon RF Transistor*

- For low noise, high-gain broadband amplifiers at collector currents from 2 mA to 30 mA
- $f_{\rm T} = 8 \text{ GHz}, F = 0.9 \text{ dB} \text{ at } 900 \text{ MHz}$
- * Short term description



ESD (Electrostatic discharge) sensitive device, observe handling precaution!

Туре	Marking	Pir	n Configura	tion	Package
BFR183F	RHs	1=B	2=E	3=C	TSFP-3

Maximum Ratings

Parameter	Symbol	Value	Unit
Collector-emitter voltage	V _{CEO}	12	V
Collector-emitter voltage	V _{CES}	20	
Collector-base voltage	V _{CBO}	20	
Emitter-base voltage	V _{EBO}	2	
Collector current	I _C	65	mA
Base current	I _B	5	
Total power dissipation ¹⁾	P _{tot}	450	mW
<i>T</i> _S ≤ 62 °C			
Junction temperature	Ti	150	°C
Ambient temperature	T _A	-65 150	
Storage temperature	T _{stg}	-65 150	

Thermal Resistance

Parameter	Symbol	Value	Unit
Junction - soldering point ²⁾	R _{thJS}	≤ 195	K/W

 $^1\mathcal{T}_S$ is measured on the collector lead at the soldering point to the pcb

 2 For calculation of $R_{\rm thJA}$ please refer to Application Note Thermal Resistance



Parameter	Symbol	Values			Unit
		min.	typ.	max.	1
DC Characteristics	• • •				•
Collector-emitter breakdown voltage	V _{(BR)CEO}	12	-	-	V
$I_{\rm C} = 1 {\rm mA}, I_{\rm B} = 0$					
Collector-emitter cutoff current	I _{CES}	-	-	100	μA
$V_{\rm CE} = 20 \text{ V}, \ V_{\rm BE} = 0$					
Collector-base cutoff current	I _{CBO}	-	-	100	nA
$V_{\rm CB} = 10 \text{ V}, I_{\rm E} = 0$					
Emitter-base cutoff current	I _{EBO}	-	-	1	μA
$V_{\rm EB} = 1 \text{V}, I_{\rm C} = 0$					
DC current gain-	h _{FE}	70	100	140	-
$I_{\rm C}$ = 15 mA, $V_{\rm CE}$ = 8 V, pulse measured					

Electrical Characteristics at $T_A = 25^{\circ}$ C, unless otherwise specified



Parameter	Symbol	Values		Unit	
		min.	typ.	max.	
AC Characteristics (verified by random sampling	1)	1			,
Transition frequency	f _T	6	8	-	GHz
$I_{\rm C} = 25 \text{ mA}, V_{\rm CE} = 8 \text{ V}, f = 500 \text{ MHz}$					
Collector-base capacitance	C _{cb}	-	0.34	0.54	pF
$V_{CB} = 10 \text{ V}, f = 1 \text{ MHz}, V_{BE} = 0$,					
emitter grounded					_
Collector emitter capacitance	C _{ce}	-	0.2	-	
$V_{CE} = 10 \text{ V}, f = 1 \text{ MHz}, V_{BE} = 0$, base grounded					
Emitter-base capacitance	C _{eb}	-	1.1	-	
$V_{\rm EB} = 0.5 \text{ V}, f = 1 \text{ MHz}, V_{\rm CB} = 0$,					
collector grounded					
Noise figure	F				dB
$I_{\rm C}$ = 5 mA, $V_{\rm CE}$ = 8 V, $Z_{\rm S}$ = $Z_{\rm Sopt}$,					
<i>f</i> = 900 MHz		-	0.9	-	
<i>f</i> = 1.8 GHz		-	1.4	-	
Power gain, maximum stable $I_{\rm C}$ = 15 mA	G _{ms}	-	21	-	dB
$I_{\rm C}$ = 15 mA, $V_{\rm CE}$ = 8 V, $Z_{\rm S}$ = $Z_{\rm Sopt}$, $Z_{\rm L}$ = $Z_{\rm Lopt}$,					
<i>f</i> = 900 MHz					
Power gain, maximum available ¹⁾	G _{ma}	-	14.5	-	dB
$I_{\rm C}$ = 15 mA, $V_{\rm CE}$ = 8 V, $Z_{\rm S}$ = $Z_{\rm Sopt}$, $Z_{\rm L}$ = $Z_{\rm Lopt}$,					
<i>f</i> = 1.8 GHz					
Transducer gain	S _{21e} ²				dB
$I_{\rm C}$ = 15 mA, $V_{\rm CE}$ = 8 V, $Z_{\rm S}$ = $Z_{\rm L}$ = 50 Ω ,					
<i>f</i> = 900 MHz		-	17	-	
<i>f</i> = 1.8 MHz		-	11	-	
Third order intercept point at output ²⁾	IP ₃	-	26	-	dBm
$V_{CE} = 8 \text{ V}, I_{C} = 15 \text{ mA}, f = 900 \text{MHz}, Z_{S} = Z_{L} = 50 \Omega$					
1dB Compression point ³⁾	P _{-1dB}	-	10.5	-	
$I_{\rm C}$ = 15 mA, $V_{\rm CE}$ = 8 V, f = 900MHz, $Z_{\rm S}$ = $Z_{\rm L}$ =50 Ω					

Electrical Characteristics at $T_A = 25^{\circ}$ C, unless otherwise specified

 ${}^{1}G_{ma} = |S_{21e} / S_{12e}| (k-(k^{2}-1)^{1/2}), G_{ms} = |S_{21} / S_{12}|$

²IP3 value depends on termination of all intermodulation frequency components.

Termination used for this measurement is 50Ω from 0.1 MHz to 6 GHz

³DC current at no input power

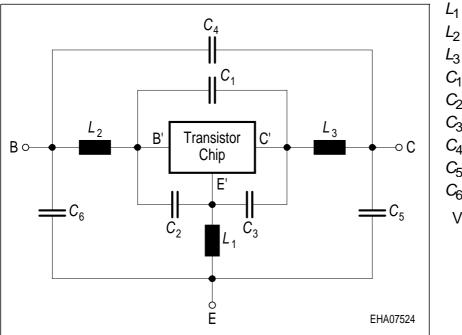


SPICE Parameter (Gummel-Poon Model, Berkley-SPICE 2G.6 Syntax):

Transitor Chip Data:								
IS =	1.0345	fA	BF =	115.98	-	NF =	0.80799	-
VAF =	14.772	V	IKF =	0.14562	А	ISE =	16.818	fA
NE =	1.2149	-	BR =	10.016	-	NR =	0.99543	-
VAR =	3.4276	V	IKR =	0.013483	А	ISC =	1.3559	fA
NC =	0.85331	-	RB =	2.5426	Ω	IRB =	0.43801	mA
RBM =	1.0112	Ω	RE =	1.3435	-	RC =	0.20486	Ω
CJE =	23.077	fF	VJE =	1.0792	V	MJE =	0.45354	-
TF =	22.746	ps	XTF =	0.36823	-	VTF =	0.50905	V
ITF =	1.8773	mA	PTF =	0	deg	CJC =	460.11	fF
VJC =	1.1967	V	MJC =	0.3	-	XCJC =	0.053823	-
TR =	1.0553	ns	CJS =	0	fF	VJS =	0.75	V
MJS =	0	-	XTB =	0	-	EG =	1.11	eV
XTI =	3	-	FC =	0.54852		TNOM	300	K

All parameters are ready to use, no scalling is necessary. Extracted on behalf of Infineon Technologies AG by: Institut für Mobil- und Satellitentechnik (IMST)

Package Equivalent Circuit:

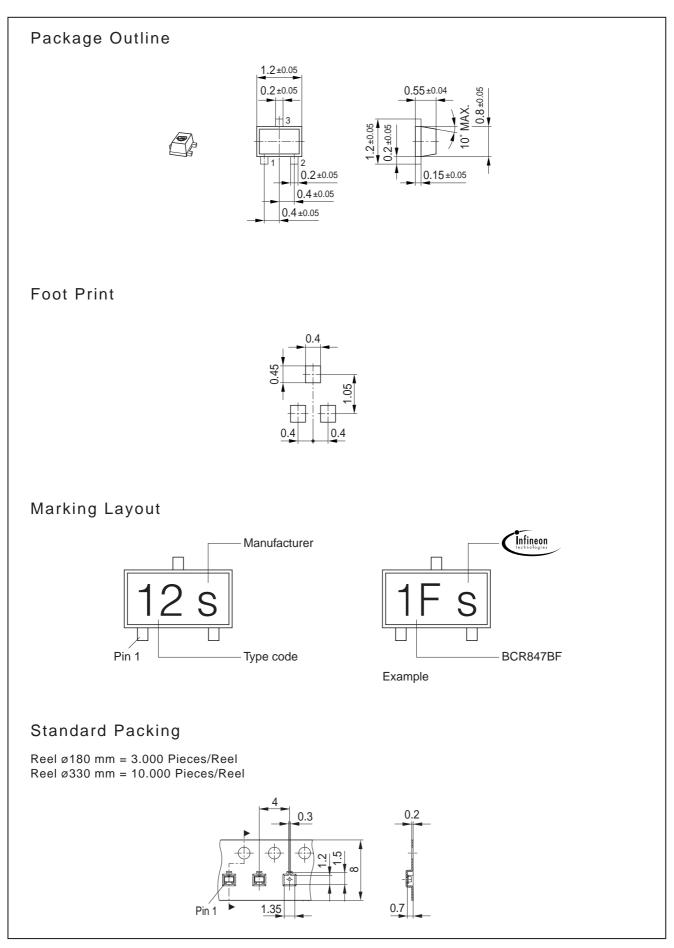


-1 =	0.556	nH
-2 =	0.675	nH
-3 =	0.381	nH
$C_1 =$	43	fF
$C_2 =$	123	fF
$C_3 =$	66	fF
C ₄ =	10	fF
$C_5 =$	36	fF
$C_{6} =$	47	fF

Valid up to 6GHz

For examples and ready to use parameters please contact your local Infineon Technologies distributor or sales office to obtain a Infineon Technologies CD-ROM or see Internet: http://www.infineon.com/silicondiscretes







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